2SC3312

Silicon NPN epitaxial planar type

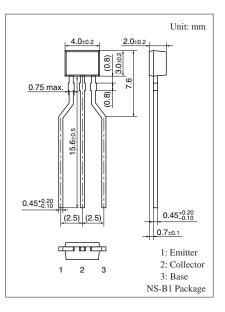
For low-frequency and low-noise amplification Complementary to 2SA1310

Features

- Optimum for high-density mounting
- Allowing supply with the radial taping
- Low noise voltage NV

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	60	V	
Collector-emitter voltage (Base open)	Base open) V _{CEO} 55		V	
Emitter-base voltage (Collector open)	V _{EBO}	7	V	
Collector current	I _C	100	mA	
Peak collector current	I _{CP}	200	mA	
Collector power dissipation	P _C	300	mW	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

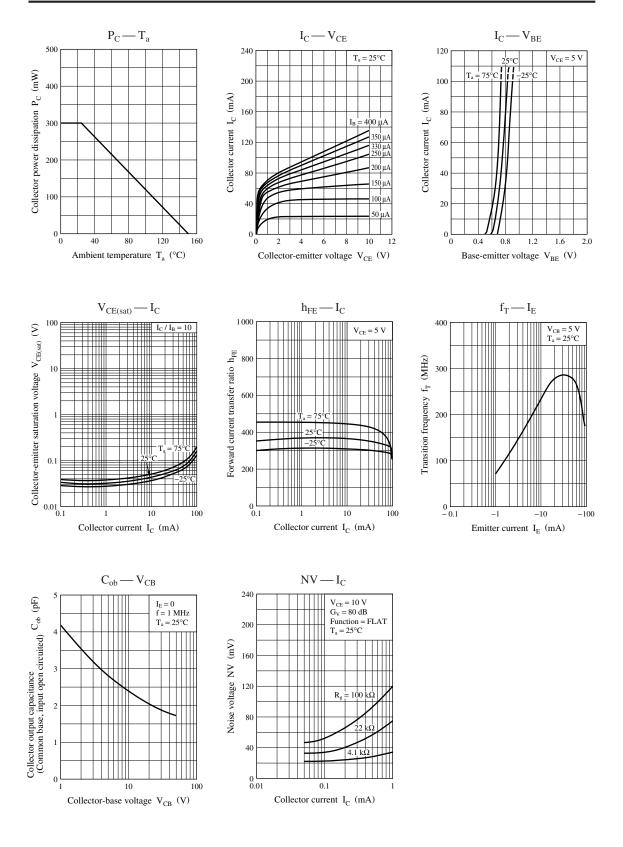
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, \ I_{\rm E} = 0$	60			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 2 {\rm mA}, I_{\rm B} = 0$	55			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$				V
Base-emitter voltage	V _{BE}	$V_{CE} = 1 \text{ V}, \text{ I}_{C} = 30 \text{ mA}$			1	V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 20 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 20 \text{ V}, I_B = 0$			1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 5 V, I_C = 2 mA$	180		700	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 100 \text{ mA}, I_{\rm B} = 10 \text{ mA}$			1	V
Transition frequency	f _T	$V_{CB} = 5 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Noise voltage	NV	$V_{CE} = 10 \text{ V}, I_C = 1 \text{ mA}, G_V = 80 \text{ dB}$			150	mV
		$R_g = 100 \text{ k}\Omega$, Function = FLAT				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	S	Т
$h_{\rm FE}$	180 to 360	260 to 520	360 to 700

Panasonic



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